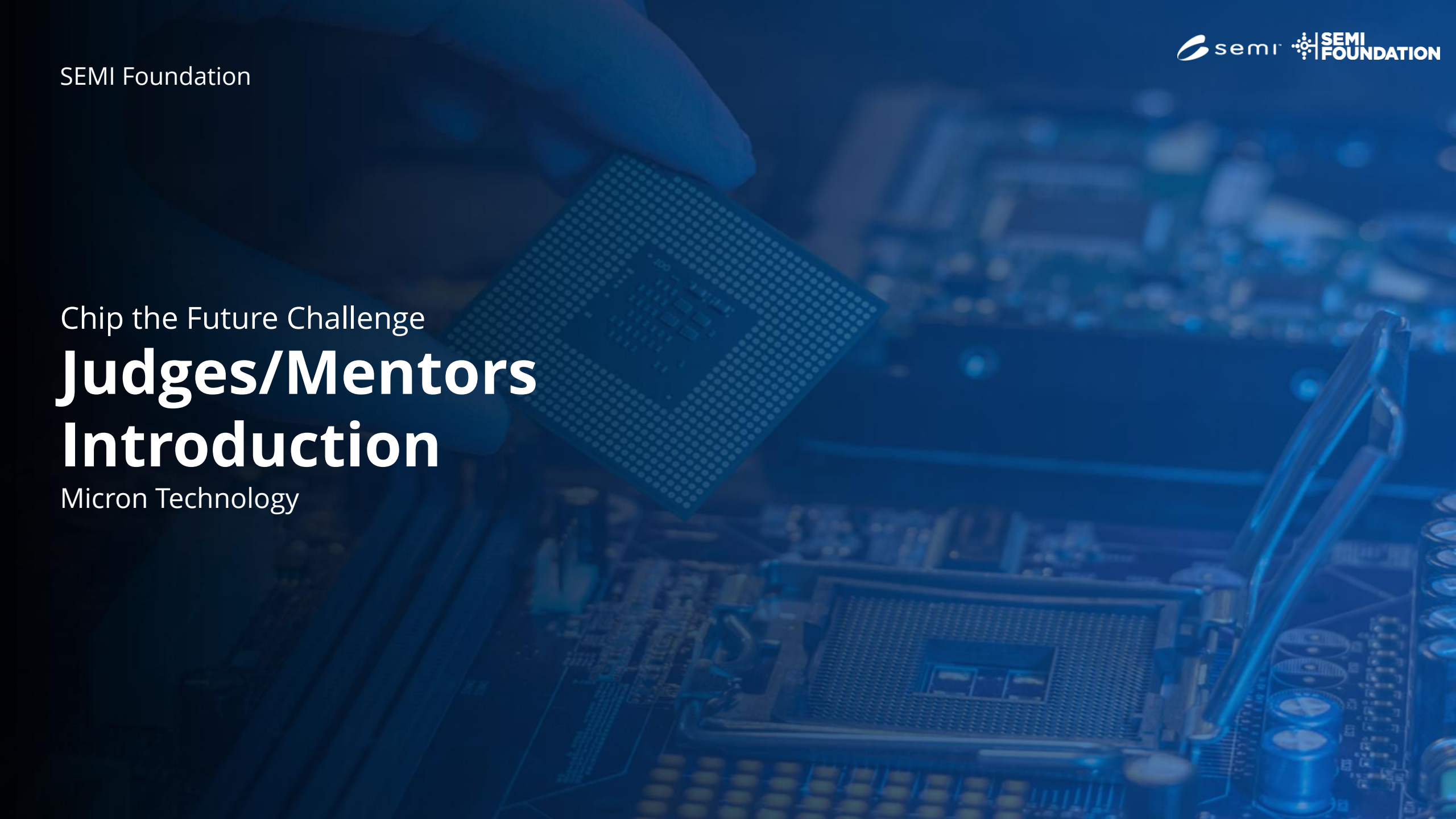
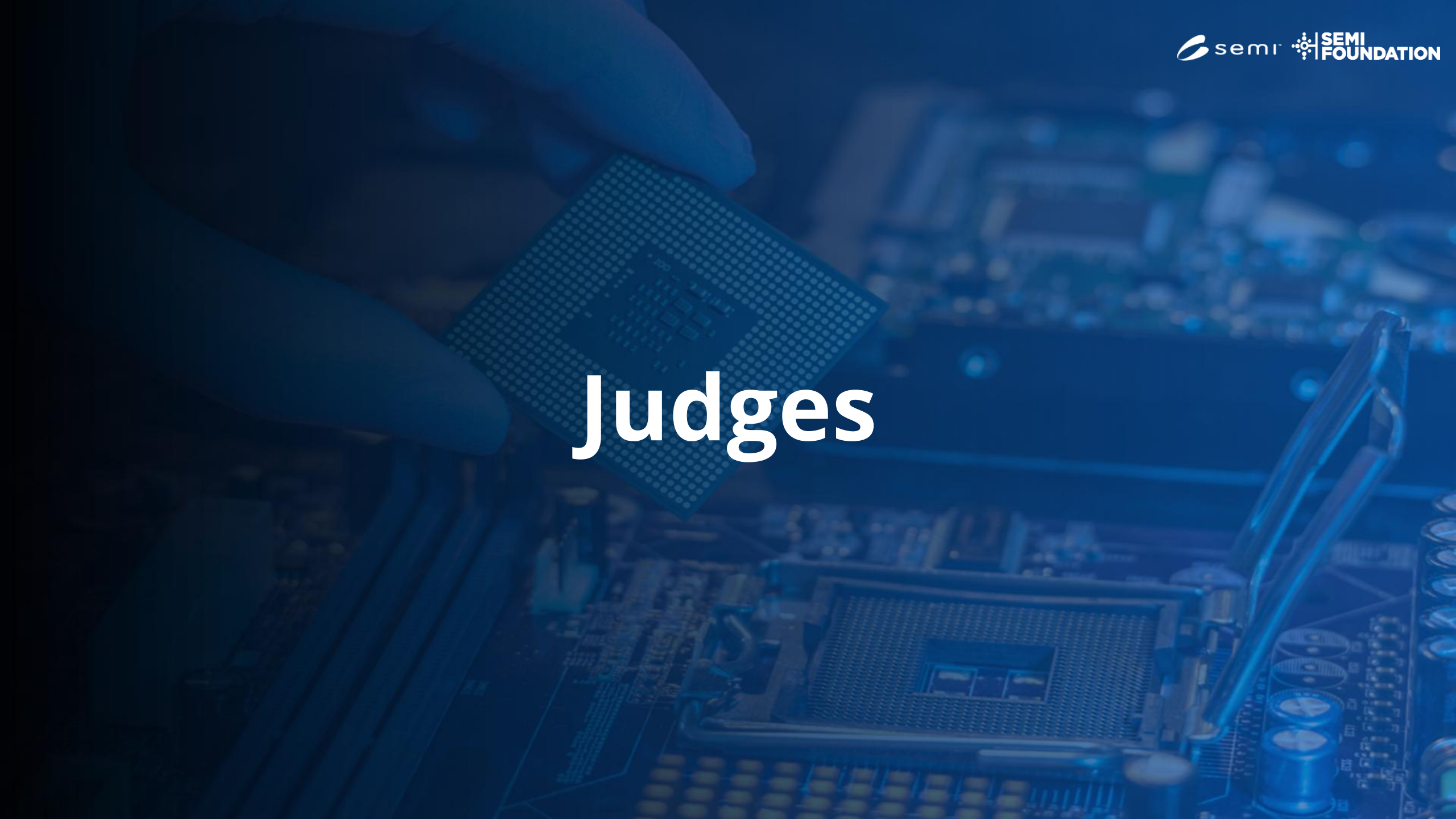
SEMI Foundation

Chip the Future Challenge

Judges/Mentors Introduction

Micron Technology





Judges



Philip Lin

Taiwan

Staff Engineer, CPIE Device organization,
Micron Technology

- Leads cross-fab initiatives in device integration, parametric monitoring, and advanced DRAM technology development, driving global technical alignment and yield improvement
- M.S. and Ph.D. in Microelectronics, National Cheng Kung University, Taiwan; 18+ years of semiconductor experience at TSMC, UMC, Winbond, and Micron
- Technical expertise in CMOS/FinFET device integration, TCAD modeling, and reliability characterization, delivering measurable improvements in yield, reliability, and process performance
- Contributed to several Micron company-first innovations; recipient of the Micron Innovation Award, holds a semiconductor device patent, and has published 18 external papers
- Mentor and mentor advisor in the MIMORY Campus Competition, guiding students and early-career engineers
- Committed to fostering innovation, technical excellence, and industry-academia collaboration to cultivate future semiconductor leaders



Kevin Song

Singapore

Member of Technical Staff, Quality Engineering Management (PQE), Micron Technology Singapore

- Supporting Fab10 WLR; focuses on electrical failure analysis, reliability engineering, and product quality
- Works with cross-functional stakeholders on root cause analysis and corrective actions to strengthen product reliability and manufacturing robustness
- Led digital transformation and AI-driven initiatives using advanced analytics, automation, and agentic AI to improve productivity and quality outcomes
- Active in university engagement and talent development; has judged student innovation programs
- Aims to inspire aspiring engineers through mentoring, judging, and outreach, and believes in cultivating future talent

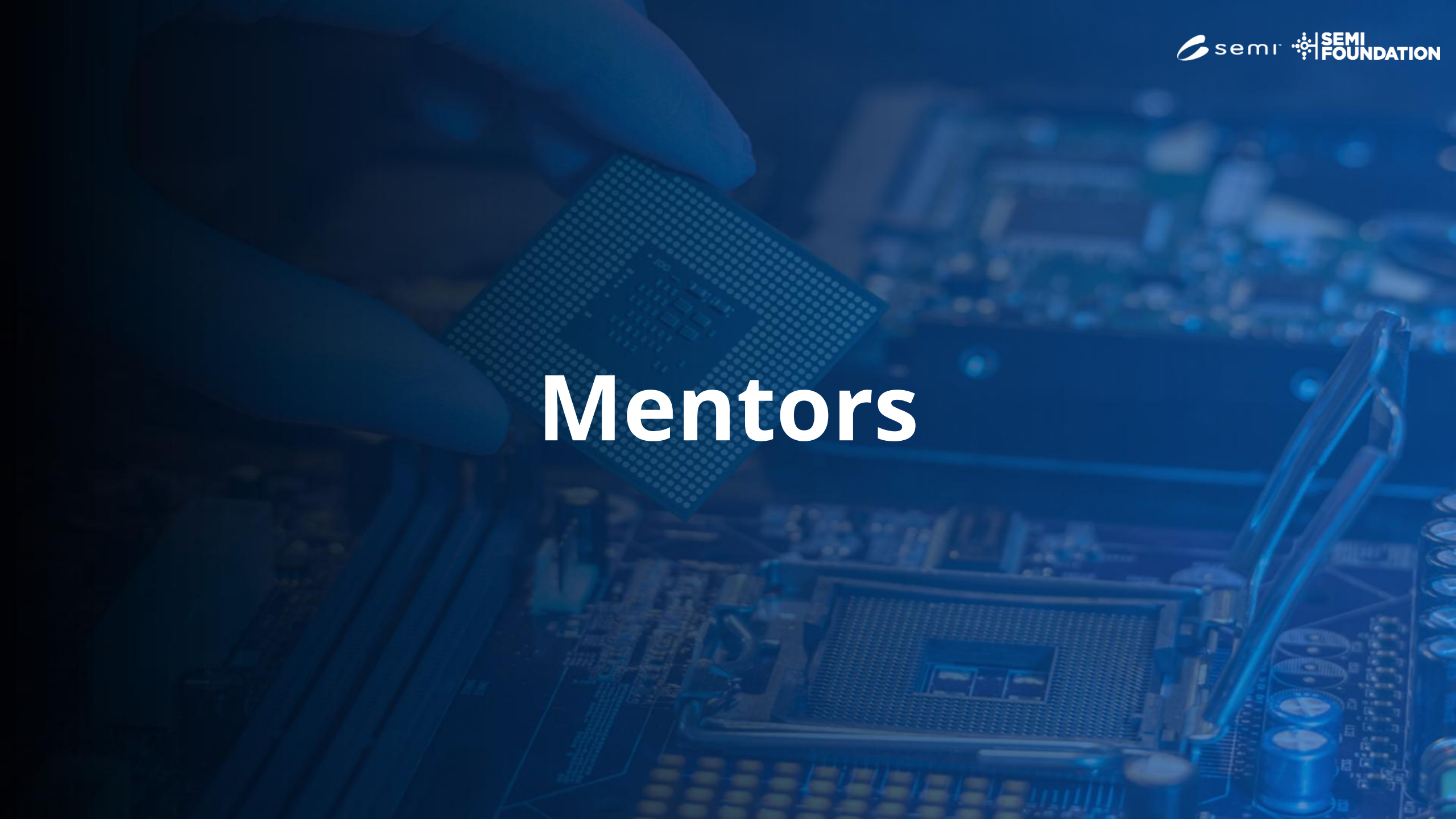


Blair Pan

China

Member of Technical Staff, System Engineer, Micron Technology (Shanghai)

- Responsible for system-level enablement and product validation of automotive storage solutions (SSD, UFS, eMMC, NAND)
- Bachelor's and Master's in Electrical Engineering, USTC; supports leading automotive OEMs and Tier 1 suppliers across infotainment, cockpit, ADAS, and autonomous driving platforms
- Technical expertise spans automotive storage systems, signal integrity, performance characterization, and system compatibility validation
- Core technical expertise: UFS, SSD, NAND Flash, System Engineering, Signal Integrity


semi
SEMI FOUNDATION
Mentors



Lubar Huang

Taiwan

Staff Engineer, Physical Failure Analysis (PFA), Micron Technology

- Drives root-cause investigations for complex DRAM failures and develops innovative characterization techniques
- M.S. in Physics, National Chiao Tung University (NCTU); built expertise in failure analysis, device physics, and advanced microscopy since joining Micron
- Technical expertise in DRAM device architecture, transistor leakage mechanisms, and SEM/TEM-based failure analysis
- Recognized with Micron Innovation Awards and Taiwan Technical Seminar (TTS) publications for advancing failure analysis capabilities
- Mentor in the MIMORY Campus Competition, sharing technical guidance with students and aspiring engineers



Ping Yu Wu

Taiwan

Principal Engineer, Central Process Integration Engineering (CPIE) RAM, Micron

- Leads global initiatives in inline monitoring and cross-fab metrology alignment
- M.S. in Electronics Engineering, NTUST; nearly 20 years of experience at TSMC, Nanya Technology, AP Memory, and Micron
- Expertise spans AFM, SPV, XPS, XRD, and data-driven metrology solutions for process control
- Recognized with multiple Micron Innovation Awards and technical publications
- Judge for the MIMORY Campus Competition; develops engineering capability through metrology training programs



Takuya Imamoto

Japan

Principal Engineer, DRAM Technology Group, Micron Memory Japan

- Develops peripheral CMOS technologies for next-generation DRAM (commodity, mobile, graphics, HBM)
- Ph.D. in Electronic Engineering, Tohoku University; JSPS Research Fellow (2012-2015); SSDM Young Researcher Award (2014)
- Contributed to Micron's first HKMG technology introduction for DRAM peripheral CMOS; now leads cross-functional transistor technology development



Kean Wei Goh

Singapore

Senior Engineer, Fab10 WLR Engineering, Micron Technology Singapore

- Supports electrical failure analysis and wafer-level reliability
- Bachelors in Electronics Engineering, Universiti Teknologi Malaysia (CGPA 3.93, Dean's List x8)
- Held leadership positions at university and founded the UTM Wushu Club, building communication and team-building skills
- Technical expertise in semiconductor manufacturing, process integration, and data-driven problem solving
- Mentor for university-focused programs, sharing industry insights with aspiring engineers



George Sim

Singapore

Senior Engineer, DRAM Test Solutions Engineering (TSE-DRAM), Micron Technology Singapore

- Part of the team developing test engineering solutions for DRAM manufacturing
- Applies engineering principles and data-driven analysis to improve manufacturing efficiency and test effectiveness, collaborating across engineering, manufacturing, and operations
- Recognized for a strong technical foundation and analytical mindset, with expertise in test optimization and troubleshooting complex engineering challenges
- Values teamwork, communication, and a culture of innovation, continuously strengthening his capabilities alongside diverse teams
- Passionate about leveraging technology to solve real-world challenges, supporting Micron's mission to transform how the world uses information



Devika Veloo

Malaysia

Senior Engineer, Package Reliability Process, Global Quality Operations, Micron Malaysia

- Leads reliability lab operations across Micron's global sites
- Drives reliability readiness for New Product Introductions, leads troubleshooting, and champions automation/AI projects; completed IATF and Global RBA audits with zero findings
- Expertise across reliability testing (HAST, temperature cycling, CSAM), lab equipment operation, and AI-assisted lab solutions
- Master of Project Management (MPM), Universiti Malaysia Pahang Al-Sultan Abdullah (UMPSA)



Amy Guo

China

Lead Principal Engineer, Package Development Engineering (PDE), Micron Technology (Xi'an)

- 15+ years of experience in advanced packaging and process development
- Leads cross-functional programs spanning technology development, product qualification, and high-volume manufacturing enablement across global teams
- Contributed to advanced packaging technology and manufacturing automation; authored technical papers, innovation disclosures, and patent-related work
- Mentors university students and early-career engineers; serves as reviewer and judge for several Micron technical seminars
- Core technical expertise: Advanced Packaging, NPI & HVM Enablement, Process Development, Yield & Productivity Optimization, Manufacturing Automation



Yan Ni

China

Staff Data Scientist, Smart Manufacturing & AI, Micron Technology (Xi'an)

- Applies data science and AI to complex semiconductor manufacturing challenges
- Current work spans manufacturing optimization, equipment health prediction, defect classification, and Generative AI agent development
- 10+ years of combined experience in data science, semiconductor engineering, and academic research across China, the US, and Japan; formerly Assistant Professor at Xi'an Jiaotong University and Senior Process Engineer at Seagate
- Ph.D. in Electrical Engineering, Iowa State University; M.S. in Data Science (University of St. Thomas) and Materials Science and Engineering (Xi'an Jiaotong University)
- Passionate mentor helping students connect rigorous technical thinking with real-world industry needs
- Core technical expertise: Manufacturing AI & Data Science, Machine Learning & Statistical Modeling, Semiconductor Process Optimization, Generative AI Agents



Ravi Solanki

India

Staff Engineer, Test Engineering, Micron Technology

- Leads strategic initiatives across Test Engineering, SBL, EFA, and New Product Proliferation for memory products
- Bachelors in Electronics and Communication Engineering, Master's in Opto Electronics (Optical Communication), and Ph.D. in Modeling and Simulation of Nanocrystal and Charge Trap Memories
- Drives electrical yield improvement, burn-in optimization, and defect containment, partnering with global engineering, manufacturing, and quality teams
- Leads automation and AI-driven initiatives (Power BI, SQL, Python, Copilot) to modernize engineering workflows and decision-making
- Mentor engineers on structured problem-solving and technical communication; established disciplined review mechanisms for yield management
- Broad expertise across yield engineering, statistical process control, and manufacturing optimization, driving continuous improvement across test and quality organizations